Maya HTT: siemens Simcenter PCB Exchange

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# ABSTRACT

This software demonstration will detail the automated work flow for preparing printed circuit assembly thermal representations for use in Simcenter 3D space vehicle models, highlighting recent enhancements to component thermal models, component thermal footprints to the board, and component underfill. We will also explore the enhanced accuracy that is offered by the explicit representation of the board copper content and traces enabled in PCB Exchange, over the more common volumetric averaging approach for board thermal conductivity.